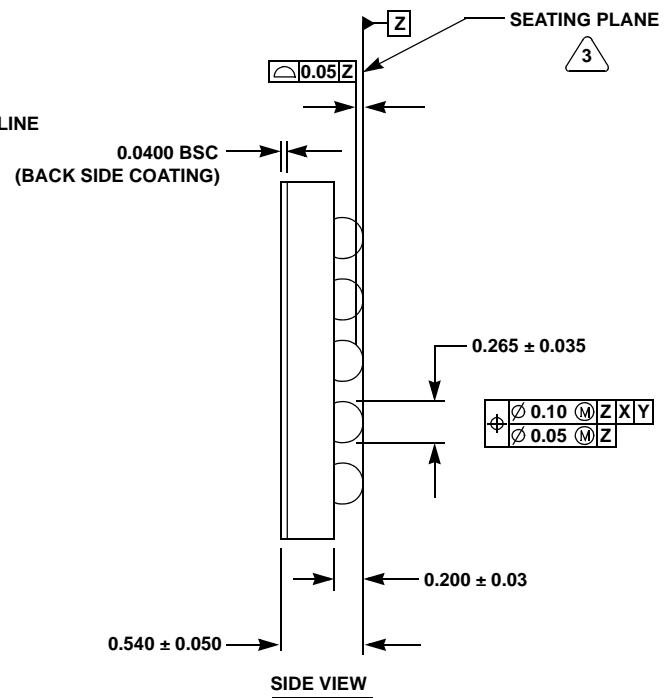
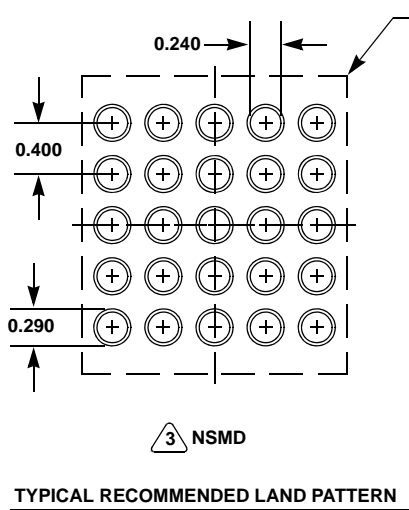
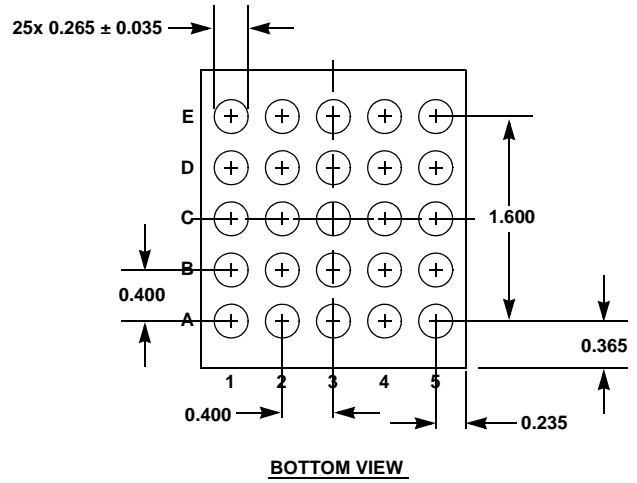
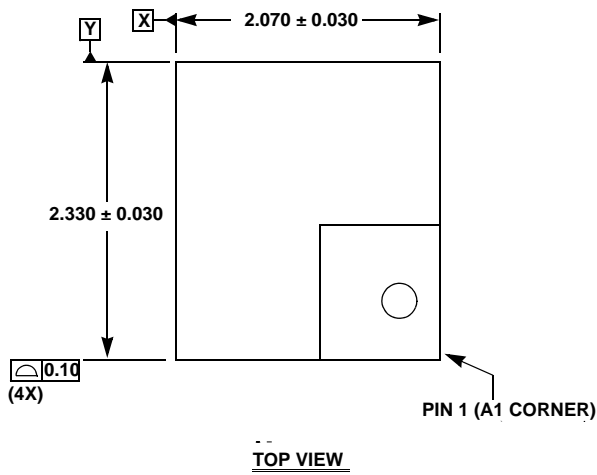


Package Outline Drawing

W5x5.25E

5X5 ARRAY 25 BALLS WITH 0.40 PITCH WAFER LEVEL CHIP SCALE PACKAGE (With BSC)

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NOTES:

1. All dimensions are in millimeters.
2. Dimension and tolerance per ASMEY 14.5M-1994, and JESD 95-1 SPP-010.
3. NSMD refers to Non-Solder Mask Defined pad design per Intersil Tech Brief TB451 located at: <http://www.intersil.com/content/dam/Intersil/documents/tb45/tb451.pdf>